Amendments to the specification:

Please amend the paragraph on page 10, line 17 to page 11, line 4 as follows:

Referring to FIG. 5, since the heat sink 34 usually made of copper has a larger CTE than the first chip 32 and the semiconductor package 33, when the package device 3 is in a temperature-increasing environment, the heat sink 34 expands to a greater extent than the first chip ~~31~~ 32 and the semiconductor package ~~device 32~~33, which may lead to deformation or warpage of the heat sink 34. However, the provision of the hollow parts 34a between the semiconductor packages 33 can alleviate this undesirable deformation or warpage of the heat sink 34 in a manner that the thermal stresses generated from the heat sink 34 can be transmitted to the hollow parts 34a and released, thereby significantly ~~reduce~~ reducing the stresses remaining in the heat sink 34. Therefore, as shown in FIG. 5, the heat sink 34 with the stress-releasing hollow parts 34a can maintain intact in structure, thereby preventing delamination of the heat sink 34 from the first chip 32 and the semiconductor package 33.